

Title (en)

LASER DRILLING OF HOLES IN MATERIALS

Title (de)

LASERBOHREN VON LÖCHERN IN MATERIALEN

Title (fr)

PER AGE PAR LASER DE TROUS DANS DES MATERIAUX

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Application

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Abstract (en)

[origin: WO9965639A1] The invention discloses methods and apparatus (1) for laser drilling of one or more holes in one or more materials (9) using a laser radiation source (2) emitting radiation having a wavelength or wavelengths, where at least some of the materials (9) have been treated to change their absorption depths at the wavelength or wavelengths of the radiation. The material or materials (9) may be treated by adding one or more dopants thereto. The material or materials (9) may comprise dielectric materials, and may be used in the construction of electrical interconnection packages such as printed circuit or wiring boards, ball grid arrays or multichip modules. The quality of the holes produced is superior so that produced when drilling undoped material with the same laser radiation source.

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